HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-8

Description

The DGD2190 is a high voltage/high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2190's high-side to switch to 600V in a bootstrap operation under high dV/dt conditions.

The DGD2190 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD2190 is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Features

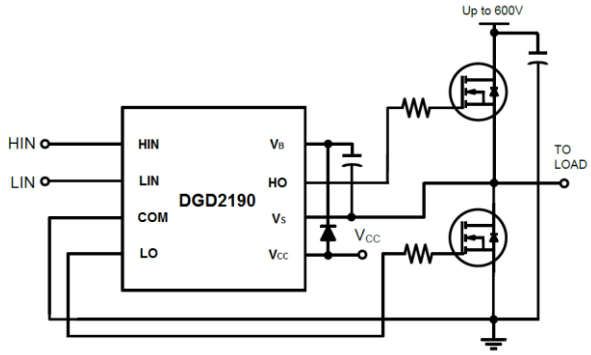
- Floating High-Side Driver in Bootstrap Operation to 600V
- Drives two N-Channel MOSFETs or IGBTs in a Half-Bridge Configuation
- Output Drivers Capable of 4.5A/4.5A Typ Sink/Source
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull-Down
- Undervoltage Lockout for High and Low-Side Drivers
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.075 grams (Approximate)



Typical Configuration



SO-8 (Type TH)
Top View

Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD2190S8-13	DGD2190	13	12	2,500

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

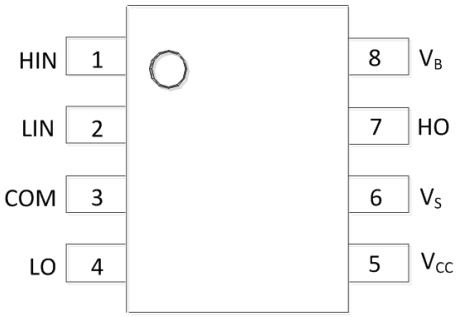
Marking Information



= Manufacturer's marking
DGD2190 = Product Type Marking Code
YY = Year (ex: 16 = 2016)
WW = Week (01 to 53)

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Pin Diagrams

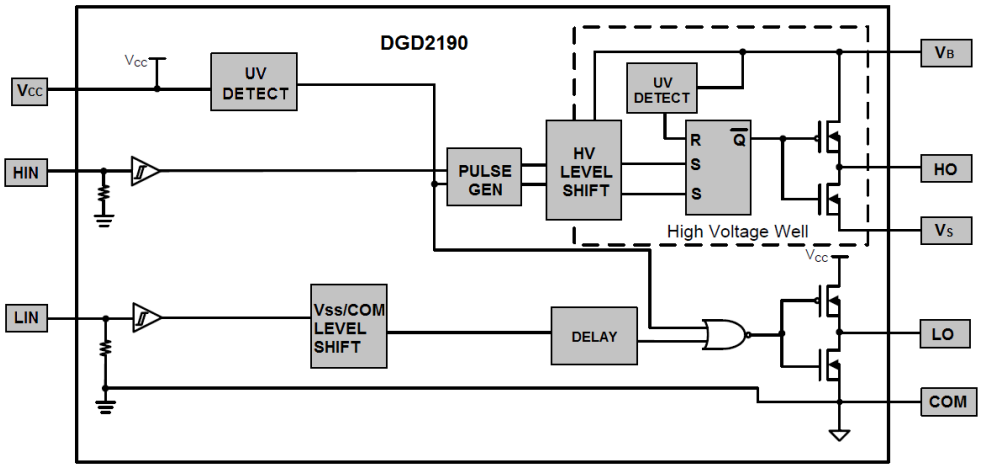


Top View: SO-8 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	HIN	Logic Input for High-side Gate Driver Output, in Phase with HO
2	LIN	Logic Input for Low-side Gate Driver Output, in Phase with LO
3	COM	Low-Side and Logic Return
4	LO	Low-Side Gate Drive Output
5	V_{CC}	Low-Side and Logic Fixed Supply
6	V_S	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V_B	High-Side Floating Supply

Functional Block Diagram



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Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	V_B	-0.3 to +624	V
High-side Floating Supply Offset Voltage	V_S	V_B -24 to V_B +0.3	V
High-side Floating Output Voltage	V_{HO}	V_S -0.3 to V_B +0.3	V
Offset Supply Voltage Transient	dV_S / dt	50	V/ns
Low-side and Logic Fixed Supply Voltage	V_{CC}	-0.3 to +24	V
Low-side Output Voltage	V_{LO}	-0.3 to V_{CC} +0.3	V
Logic Input Voltage (HIN and LIN)	V_{IN}	-0.3 to V_{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	45	°C/W
Operating Temperature	T_J	+150	°C
Storage Temperature Range	T_{STG}	-55 to +150	

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-side Floating Supply Absolute Voltage	V_B	V_S +10	V_S +20	V
High-side Floating Supply Offset Voltage	V_S	(Note 6)	600	V
High-side Floating Output Voltage	V_{HO}	V_S	V_B	V
Low-side Fixed Supply Voltage	V_{CC}	10	20	V
Low-side Output Voltage	V_{LO}	0	V_{CC}	V
Logic Input Voltage (HIN and LIN)	V_{IN}	0	5	V
Ambient Temperature	T_A	-40	+125	°C

Notes: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to -V_{BS}.

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DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage	V_{IH}	2.5	—	—	V	V_{CC} = 10V to 20V
Logic "0" Input Voltage	V_{IL}	—	—	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, V_{BIAS} - V_O	V_{OH}	—	—	0.1	V	I_O = 0mA
Low Level Output Voltage, V_O	V_{OL}	—	—	0.035	V	I_O = 0mA
Offset Supply Leakage Current	I_{LK}	—	—	50	µA	V_B = V_S = 600V
Quiescent V_{BS} Supply Current	I_{BSQ}	—	45	80	µA	V_{IN} = 0V or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	—	75	200	µA	V_{IN} = 0V or 5V
Logic "1" Input Bias Current	I_{IN+}	—	25	50	µA	V_{IN} = 5V
Logic "0" Input Bias Current	I_{IN-}	—	1.0	2.0	µA	V_{IN} = 0V
V_{BS} Supply Undervoltage Positive Going Threshold	V_{BSUV+}	7.6	8.4	9.8	V	—
V_{BS} Supply Undervoltage Negative Going Threshold	V_{BSUV-}	6.9	7.8	9.0	V	—
V_{CC} Supply Undervoltage Positive Going Threshold	V_{CCUV+}	7.6	8.4	9.8	V	—
V_{CC} Supply Undervoltage Negative Going Threshold	V_{CCUV-}	6.9	7.8	9.0	V	—
V_{CC} and V_{BS} Undervoltage Hysteresis	V_{CCUVH}	—	0.6	—	V	—
	V_{BSUVH}	—	0.6	—	V	—
Output High Short Circuit Pulsed Current	I_{O+}	3.5	4.5	—	A	V_O = 0V, PW ≤ 10ms
Output Low Short Circuit Pulsed Current	I_{O-}	3.5	4.5	—	A	V_O = 15V, PW ≤ 10ms

Note: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins; HIN and LIN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-On Propagation Delay	t_{ON}	—	140	200	ns	V_S = 0V
Turn-Off Propagation Delay	t_{OFF}	—	140	200	ns	V_S = 0V
Delay Matching, HO & LO Turn On/Off	t_{DM}	—	0	50	ns	—
Turn-On Rise Time	t_R	—	25	50	ns	V_S = 0V
Turn-Off Fall Time	t_F	—	20	45	ns	V_S = 0V

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Timing Waveforms

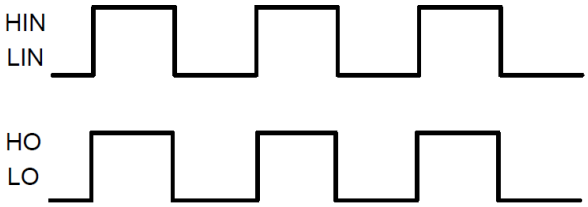


Figure 1. Input / Output Timing Diagram

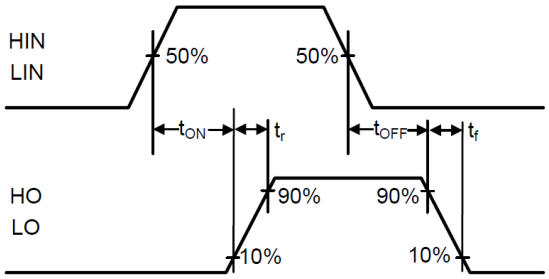


Figure 2. Switching Time Waveform Definitions

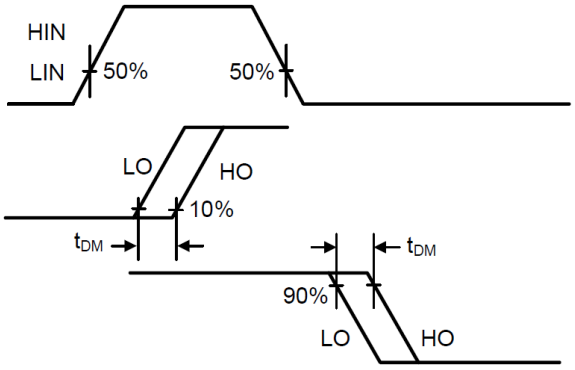


Figure 3. Delay Matching Waveform Definitions

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Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

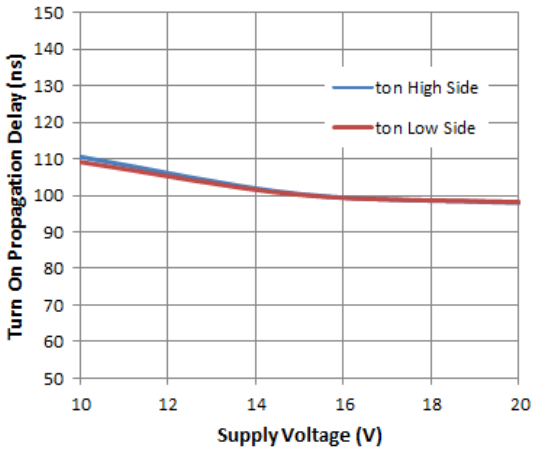


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

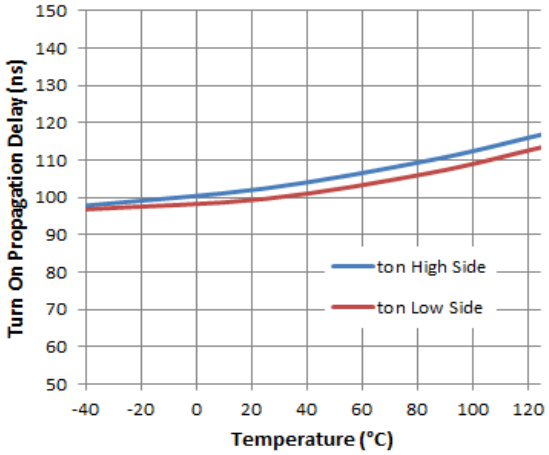


Figure 5. Turn-on Propagation Delay vs. Temperature

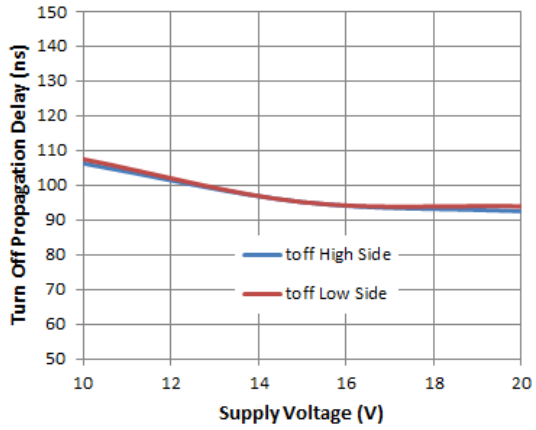


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

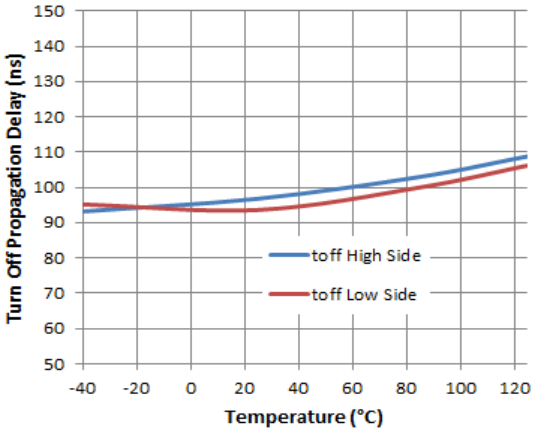


Figure 7. Turn-off Propagation Delay vs. Temperature

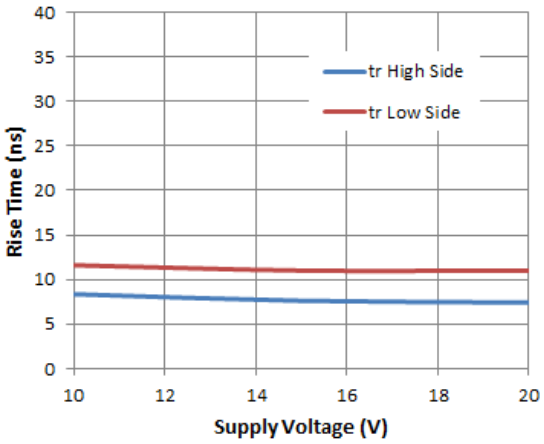


Figure 8. Rise Time vs. Supply Voltage

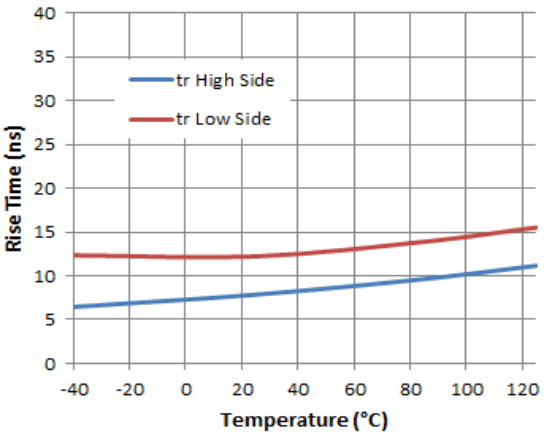


Figure 9. Rise Time vs. Temperature

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Typical Performance Characteristics (Cont.) (@T_A = +25°C, unless otherwise specified.)

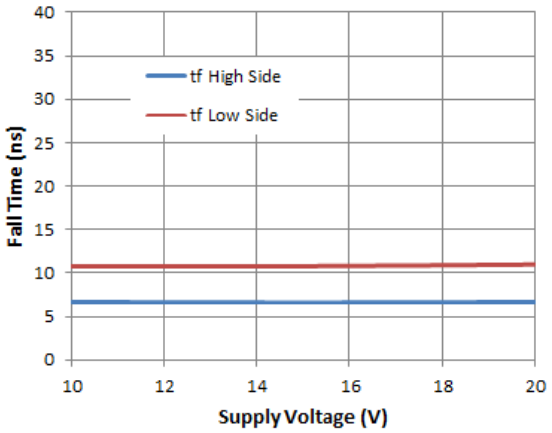


Figure 10. Fall Time vs. Supply Voltage

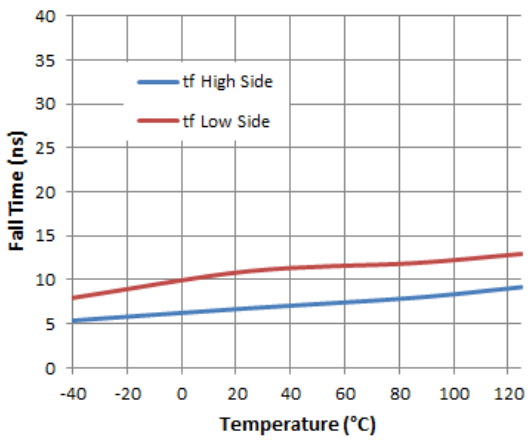


Figure 11. Fall Time vs. Temperature

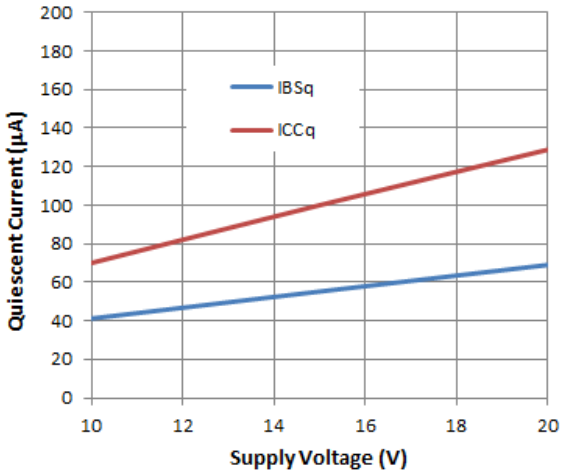


Figure 12. Quiescent Current vs. Supply Voltage

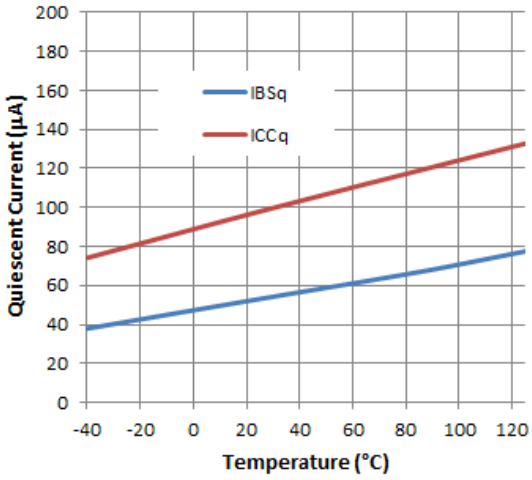


Figure 13. Quiescent Current vs. Temperature

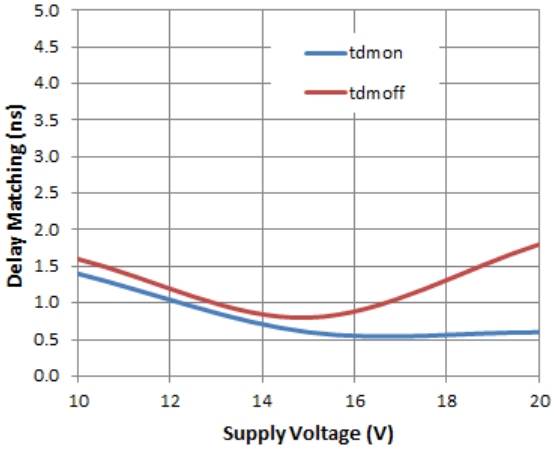


Figure 14. Delay Matching vs. Supply Voltage

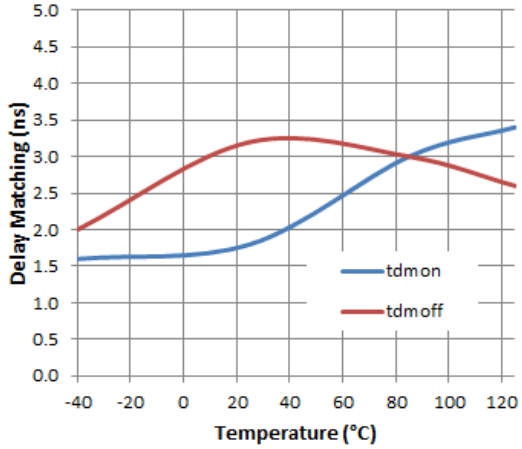


Figure 15. Delay Matching vs. Temperature

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Typical Performance Characteristics (Cont.) (@T_A = +25°C, unless otherwise specified.)

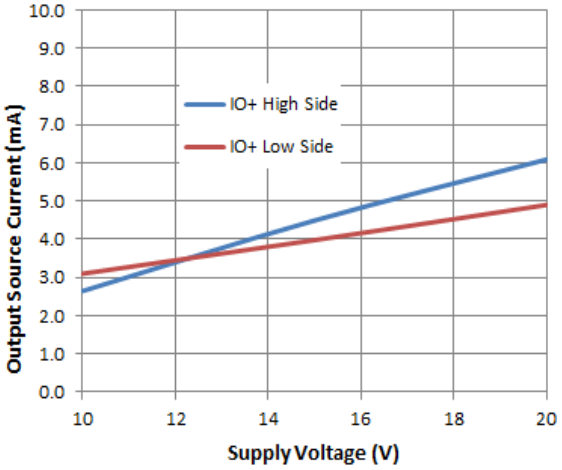


Figure 16. Output Source Current vs. Supply Voltage

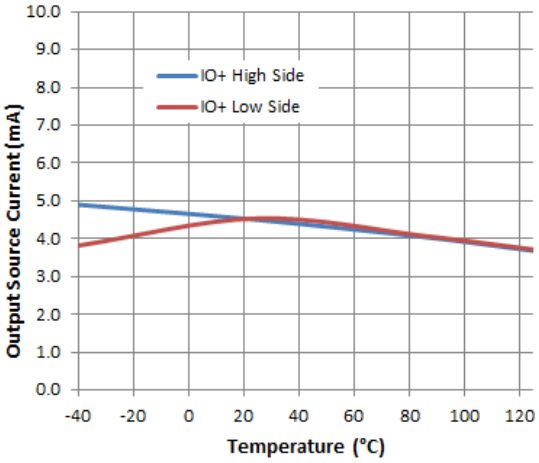


Figure 17. Output Source Current vs. Temperature

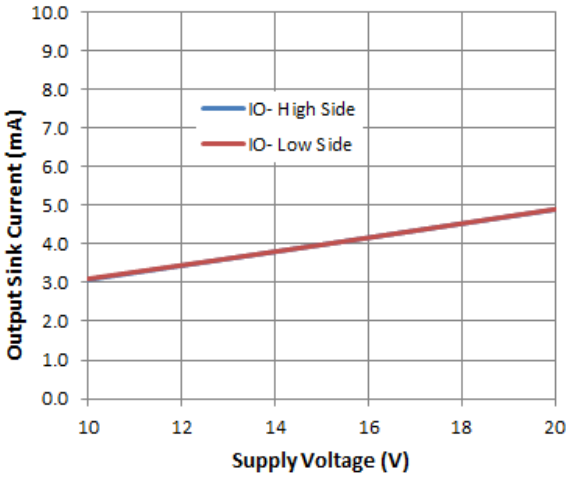


Figure 18. Output Sink Current vs. Supply Voltage

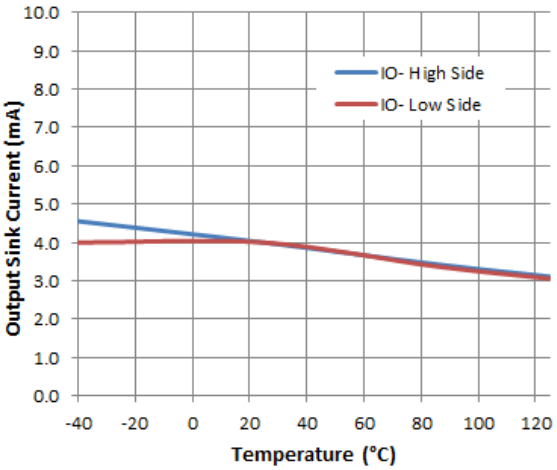


Figure 19. Output Sink Current vs. Temperature

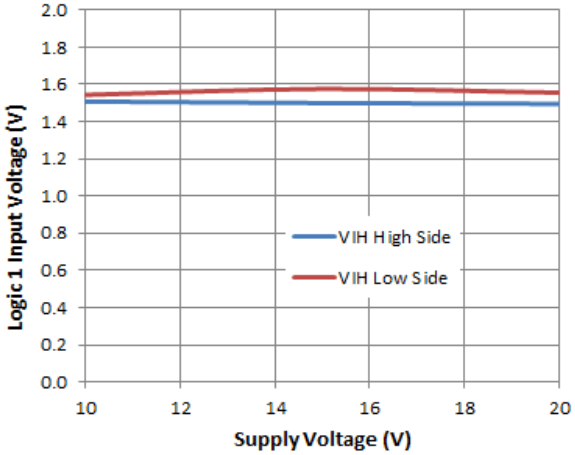


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

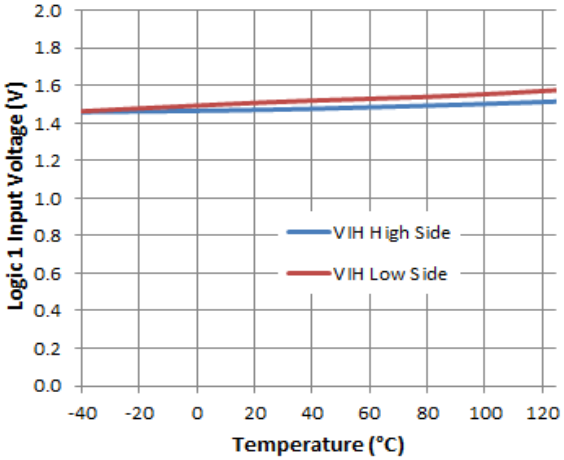


Figure 21. Logic 1 Input Voltage vs. Temperature

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Typical Performance Characteristics (Cont.) (@T_A = +25°C, unless otherwise specified.)

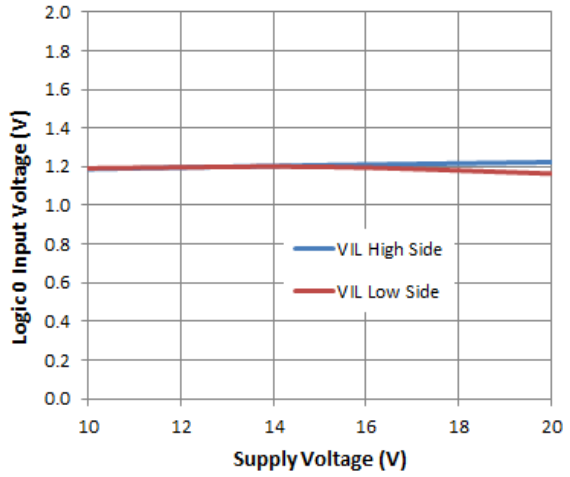


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

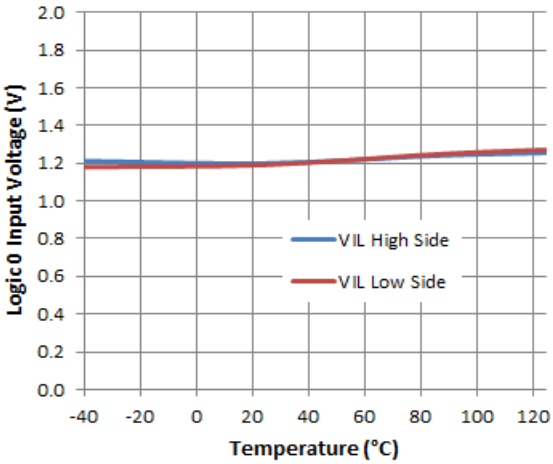


Figure 23. Logic 0 Input Voltage vs. Temperature

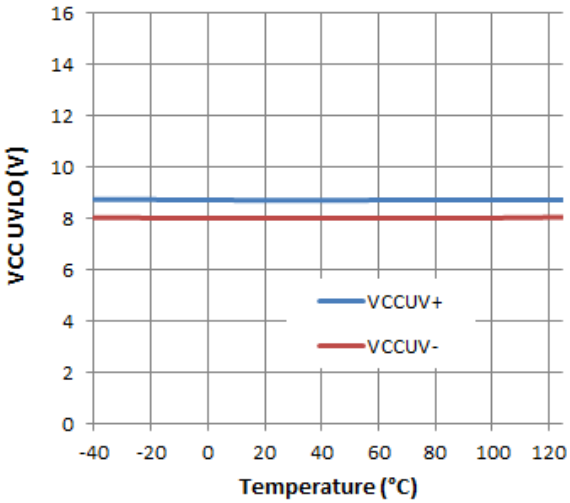


Figure 24. VCC UVLO vs. Temperature

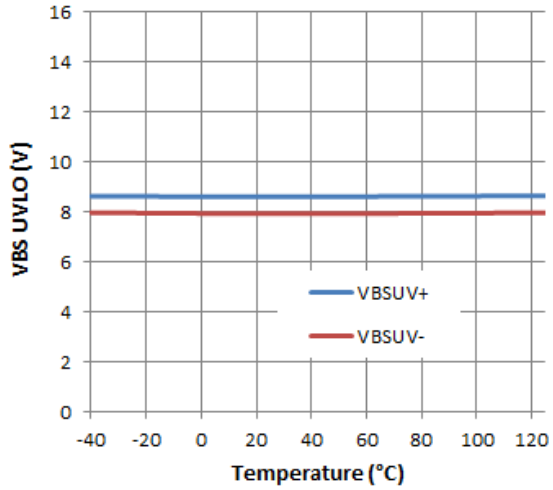


Figure 25. VBS UVLO vs. Temperature

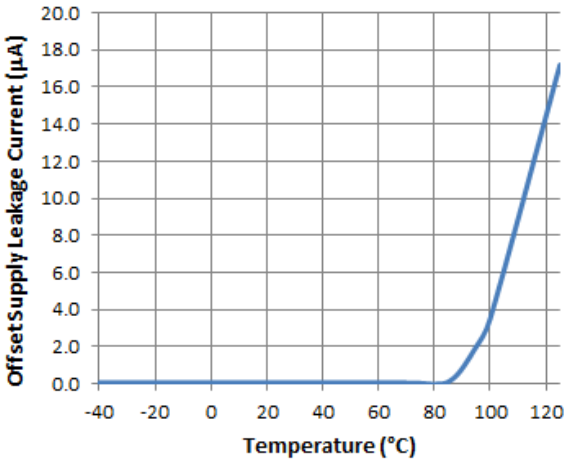


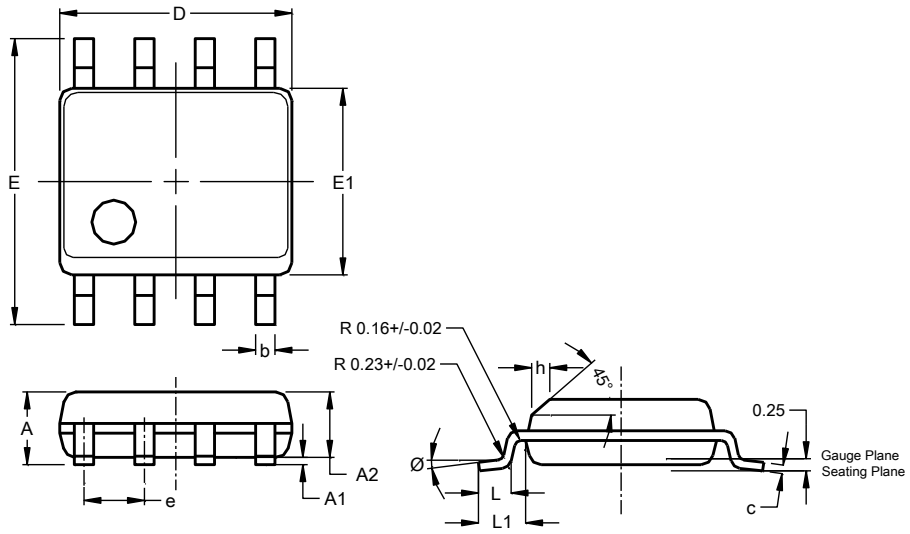
Figure 26. Offset Supply Leakage Current vs. Temperature

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Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)

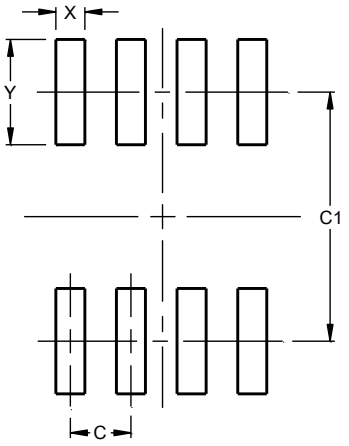


SO-8 (Type TH)			
Dim	**Min**	**Max**	**Typ**
A	1.35	1.75	–
A1	0.10	0.25	–
A2	–	–	1.45
b	0.35	0.51	–
c	0.190	0.248	–
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	–	–	1.27
h	0.25	0.50	–
L	0.41	1.27	–
L1	–	–	1.04
Ø	0°	8°	–
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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